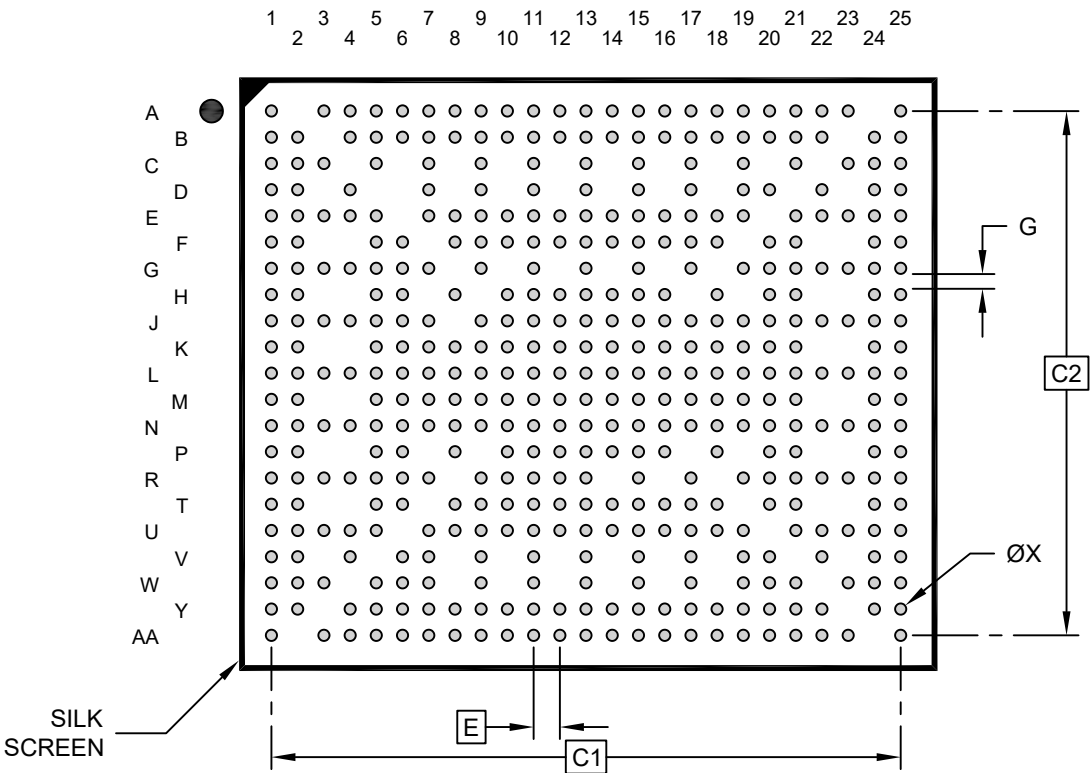


427-Ball Thin Fine-Pitch Ball Grid Array (4UB) - 21x18x1.2 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1	19.20 BSC		
Contact Pad Spacing	C2	16.00 BSC		
Contact Pad Width (Xnn)	X			0.35
Contact Pad to Contact Pad (Xnn)	G	0.45		

Notes:

- 1. Dimensioning and tolerancing per ASME Y14.5M
- BSC: Basic Dimension. Theoretically exact value shown without tolerances.